

### **REMARKS**

Claims 1 to 6, 8 to 10, and 21 to 23 are pending.

Claim 7, and claims 11 to 20 relating to a method of making contact pressure sensor, have been cancelled without prejudice. Claim 8 has been rewritten in independent form. New claims 21 to 23 are presented for consideration by the Examiner. The claims have been amended to more clearly define the present invention.

The Examiner has rejected claim 1 under 35 U.S.C. 102(b) as anticipated by U.S. Patent No. 5,894,161 (hereinafter D1). Claims 2-4 and 9-10 have been rejected under 35 U.S.C. 103(a) as obvious in view of D1 and U.S. Patent No. 5,429,993 (hereinafter D2). Claims 5-7 have been rejected under 35 U.S.C. 103(a) as obvious in view of D1 and U.S. Patent No. 6,555,946 (hereinafter D3). The Applicants respectfully disagree.

Specifically, amended independent claim 1 recites, inter alia:

a contact pressure sensitive layer comprising a material with piezo-resistive properties, the contact pressure sensitive layer having a lattice structure different to the substrate and being disposed between the substrate and the first contact surface;

a supporting layer disposed between the contact pressure sensitive layer and the substrate, the supporting layer of having a lattice-matched structure to that of the contact pressure sensitive layer;...

The Applicants respectfully submit that none of the cited documents D1-D3 disclose at least the above features of amended independent claim 1. There is no clear and unmistakable direction of the above features in the disclosure of each of the cited documents D1-D3. Thus, the Applicants respectfully submit that independent claim 1 is novel over the cited documents.

More specifically, contrary to the present invention, there is no disclosure of any requirement in relation to lattice structures either matching or being different between respective layers in the device of D1. More particularly, there is no disclosure of a supporting layer having a lattice-matched structure to that of the contact pressure sensitive layer being disposed between the contact pressure sensitive layer and the substrate. For example, in D1, as shown in Figure 3B (column 5, line 64 to column 6, lines 1-10), the piezoresistive sensing layer 54 is disposed directly onto the base 56. Furthermore, there is no disclosure in D1 of the supporting layer and the contact pressure sensitive layer being lattice-matched and being disposed on a substrate having a different lattice structure to the contact pressure sensitive layer.

Advantages of the device as required by amended independent claim 1 can be found throughout the specification. For example, by having a supporting layer and a contact pressure sensitive layer that are lattice-matched, the contact pressure sensitive layer can be transferred (via the supporting layer) onto a substrate with a different lattice structure to the contact pressure sensitive layer. Therefore, a substrate with more robust qualities to withstand higher contact pressures may be chosen. This is not disclosed in any one of the cited documents D1-D3.

Further to the above, the applicant submits that there is neither any suggestion in the cited documents D1-D3 nor any motivation to modify the cited disclosures to arrive at the claimed subject matter of the present invention. Therefore, the Applicants respectfully submit that, the present claims are inventive over the cited art.

Since claims 2 to 6, 9 and 10 either depend directly or indirectly from claim 1, it is submitted that these dependent claims are also novel and inventive over the cited references.

In view of the above, the Applicant respectfully submits that all the pending claims are allowable over the art of record.

Appl. No. 10/615,413  
Response dated April 24, 2006

The Description has been amended to correct typographical errors. Specifically, "IIB" and "VB" have been replaced with "IIIA" and "VA", respectively.

In view of the foregoing, favourable consideration and allowance of the application are earnestly solicited.

Respectfully submitted,

DINSMORE & SHOHL LLP

By\_\_\_\_/ James E. Beyer /\_\_\_\_\_  
James E. Beyer  
Registration No. 39,564

One Dayton Centre  
One South Main Street, Suite 1300  
Dayton, Ohio  
45402

Tel.: (937) 449-6400  
Fax: (937) 449-6405

MZ/JJP/kew  
April 23, 2006